

# Material Composition Specification

DO-15 Case

Available with Pb (lead)-free plating\*



Device average mass ..... 420 mg  
Fluctuation margin ..... +/-10%

Device part	Substance	mass (mg)
active device	doped Si	1.90
leadframe	Copper Alloy	303
die attach	Pb92.5Ag2.5Sn5	1.30
*plating	SnPb10 or Sn (100% tin, Pb-free)	4.80 4.80
encapsulation	partially brominated epoxy  -silica  -epoxy < 20%  -resin < 10%  -Sb <sub>2</sub> O <sub>3</sub> < 1.0%	109

\* specify Lead-free when ordering 100% tin (Pb-free) plating option.